## IN THE CLAIMS:

Please cancel claims 50, 61, and 65-72 without prejudice, and amend claims 46, 48-49, 51, 56, 62, and 64 as follows:

Claims 1-45 (Canceled)

46. (Currently amended) A semiconductor processing system, comprising:

a mini-environment coupled to a wafer cassette;

a robot disposed within the mini-environment;

one or more load lock chambers connected to the mini-environment; and

one or more process chambers connected to the one or more load lock chambers, wherein each load lock chamber is connected to a single process chamber, wherein each load lock chamber comprises:

an enclosure having a bottom, a lid and sidewalls defining a chamber cavity, wherein one or more perforations are disposed in the bottom;

one or more lift pins slidably disposed through the one or more perforations; and

a transfer robot disposed in each load lock chamber.

## 47. (Canceled)

- 48. (Currently amended) The system of claim  $\underline{46}$  47, wherein a central portion of each chamber cavity has a diameter slightly larger than a diameter of a substrate to be received in the system.
- 49. (Currently amended) The system of claim <u>46</u> 47, wherein each load lock chamber is connected to the single process chamber in a linear configuration.
- 50. (Canceled)

- 51. (Currently amended) The system of claim <u>46</u> 50, wherein the load lock chamber further comprises a cover having an opening and the lid is adapted to substantially cover the opening.
- 52. (Previously presented) The system of claim 51, wherein the lid further comprises at least one stabilizing rod disposed through the lid and connected to the cover.
- 53. (Previously presented) The system of claim 52, wherein the lid further comprises a bellow sleeves disposed around a lower portion of the stabilizing rod.
- 54. (Previously presented) The system of claim 46, further comprising a vacuum pump connected to the load lock chamber.
- 55. (Previously presented) The system of claim 48, wherein the load lock chamber further comprises:

an elongated substantially rectangular aperture; and a hermetic sealing apparatus adapted to substantially cover the aperture.

56. (Currently amended) A semiconductor processing system for processing substrates, comprising:

a mini-environment coupled to a wafer cassette;

a robot disposed within the mini-environment;

one or more load lock chambers connected to the mini-environment, each load lock chamber comprising:

an enclosure having a bottom, a lid and sidewalls defining a chamber cavity having a central portion having a diameter slightly larger than a diameter of the substrates to be received in the system, wherein one or more perforations are disposed in the bottom;

one or more lift pins slidably disposed through the one or more perforations; and

a transfer robot disposed in each load lock chamber, wherein each transfer robot comprises:

one or more actuators;

a linkage; and

a substrate support means; and

one or more process chambers connected to the one or more load lock chambers, wherein each load lock chamber is connected to a single process chamber.

- 57. (Previously presented) The system of claim 56, wherein each load lock chamber is fluidly connected to the single process chamber via a substantially rectangular aperture.
- 58. (Previously presented) The system of claim 57, wherein the load lock chamber further comprises a hermetic seal adapted to substantially cover the aperture.
- 59. (Previously presented) The system of claim 58, wherein the load lock chamber further comprises:

a cover having an opening and the lid is adapted to substantially cover the opening.

- 60. (Previously presented) The system of claim 59, further comprising: a transfer assembly adapted to transfer the substrates to a plurality of positions.
- 61. ► (Canceled)
- 62. (Currently amended) The system of claim 61 56, wherein the lift pins are coupled at one end to a linear actuator.
- 63. (Previously presented) The apparatus of claim 56, wherein a vacuum pump is in fluid communication with the load lock chamber.



64. (Currently amended) The system of claim 61 56, wherein the lid further comprises:

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at least one stabilizing rod disposed through the lid and connected to the cover; and

a bellow sleeves disposed around a lower portion the stabilizing rod.

Claims 65 72 (Canceled)